

SPECIFICATION FOR RoHS 6 COMPLIANT SMT TCXO

MtronPTI P/N M6164S023

Electrical Specifications:

Parameter	Symbol	Min.	Typ.	Max.	Units	Conditions
Frequency of Operation	F _O		10.000000		MHz	
Frequency Stabilities						
vs Temperature	ΔF/F	-1.2		+1.2	ppm	Includes initial accuracy @ +25°C & deviation over operating temperature range.
vs Aging		-4.0		+4.0	ppm	10 years @ +55°C
vs Shock and Vibration		-0.7		+0.7		
vs. Supply	F _{VS}		± 0.02	± 0.1	ppm	For 5% voltage change
vs. Load	F _L		± 0.02	± 0.1	ppm	For 5% load change
vs Reflow		-0.3		+0.3	ppm	
Total Frequency Stability		-6.0		+6.0		All inclusive 10 years
Output						
Output Type		Clipped Sine Wave				
Output Load		10kΩ // 10pF			pF	
Output Level	V _{OUT}	0.8			V _{pk-pk}	
Tri-state Function		Logic "1", or floating, output Enabled. Logic "0", output Disabled.				Pad 8
Start-up Time	T _{SU}			10	mS	
Additional Specifications						
SSB Phase Noise (Under Static Conditions)			-100		dBc/Hz	@ 10Hz Offset
			-128			@ 100Hz Offset
			-148			@ 1kHz Offset
			-155			@ 10kHz Offset
			-156			@ 100kHz Offset
			-157			@ 1MHz Offset
G-sensitivity			0.6		ppb/g	
Supply Voltage & Power Consumption						
Operating Voltage	V _{DD}	+2.85	+3.0	+3.15	V _{DC}	
Operating Current	I _{DD}			5	mA	

Environmental & Mechanical Requirements:

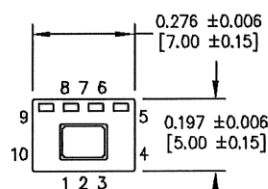
Operating Temperature	T _A	-40		+85	°C	
Storage Temperature	T _S	-55		+125	°C	
Mechanical Shock	Per MIL-STD-202, Method 213, Condition C (100 g's, 6 ms duration, ½ sine wave)					
Vibration	Per MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)					
Solderability	Per MIL-STD-202, Method 208, except steam aging is not required					
Max. Soldering Conditions	See solder profile, Figure 1					
Package Type	5.0 x 7.0 x 1.6mm, 10-pad Ceramic Leadless Chip Carrier. RoHS Compliant.					

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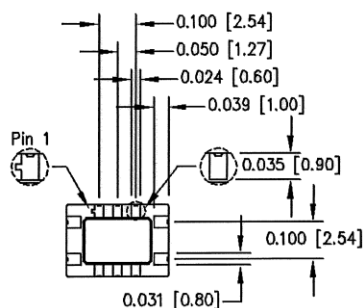
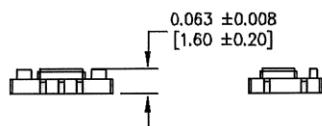
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Mechanical, Marking and Layout Information:

Pad	Function
1	N/C
2	N/C
3	N/C
4	Ground/Case
5	Output
6	N/C
7	N/C
8	Tristate
9	+V _{DD}
10	N/C



All dimensions
in inches [mm].



SUGGESTED SOLDER PAD LAYOUT

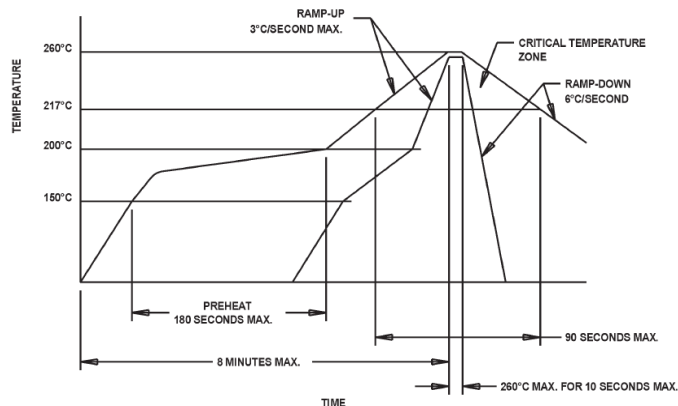
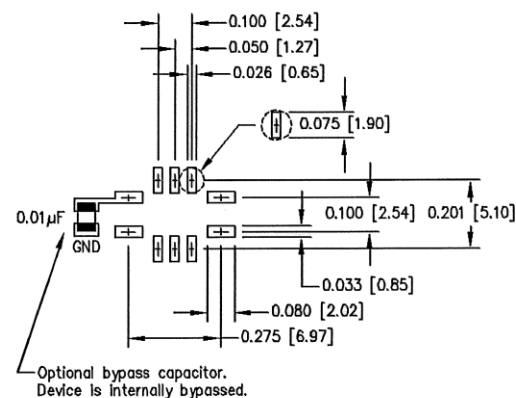


Figure 1

Data Sheet Revision Table:

Date	Rev.	Author	Details of Revision
01/12/15	0	MM	Original Release.
01/27/15	A	MM	Combined initial accuracy @ +25°C and deviation over operating temperature range.